DERWENT-ACC-NO: 2002-301636

DERWENT-WEEK: 200234

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TITLE: Stack type package

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PATENT-ASSIGNEE: HYNIX SEMICONDUCTOR INC [HYNIN]

PRIORITY-DATA: 2000KR-0000623 (January 7, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
KR 2001068614 A	July 23, 2001	N/A	001	H01L 023/12

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO	APPL-DATE
KR2001068614A	N/A	2000KR-0000623	January 7, 2000

INT-CL (IPC): H01L023/12

ABSTRACTED-PUB-NO: KR2001068614A

BASIC-ABSTRACT:

NOVELTY - A stack type package is provided to prevent quality defect due to heat generated when an upper single package and a lower single package are electrically connected to each other by connecting the packages using a connecting wires.

DETAILED DESCRIPTION - A BLP type upper single package(20) and an SOP type lower single package(30) are vertically disposed, and the upper/lower packages(20,30) are electrically connected by a connecting

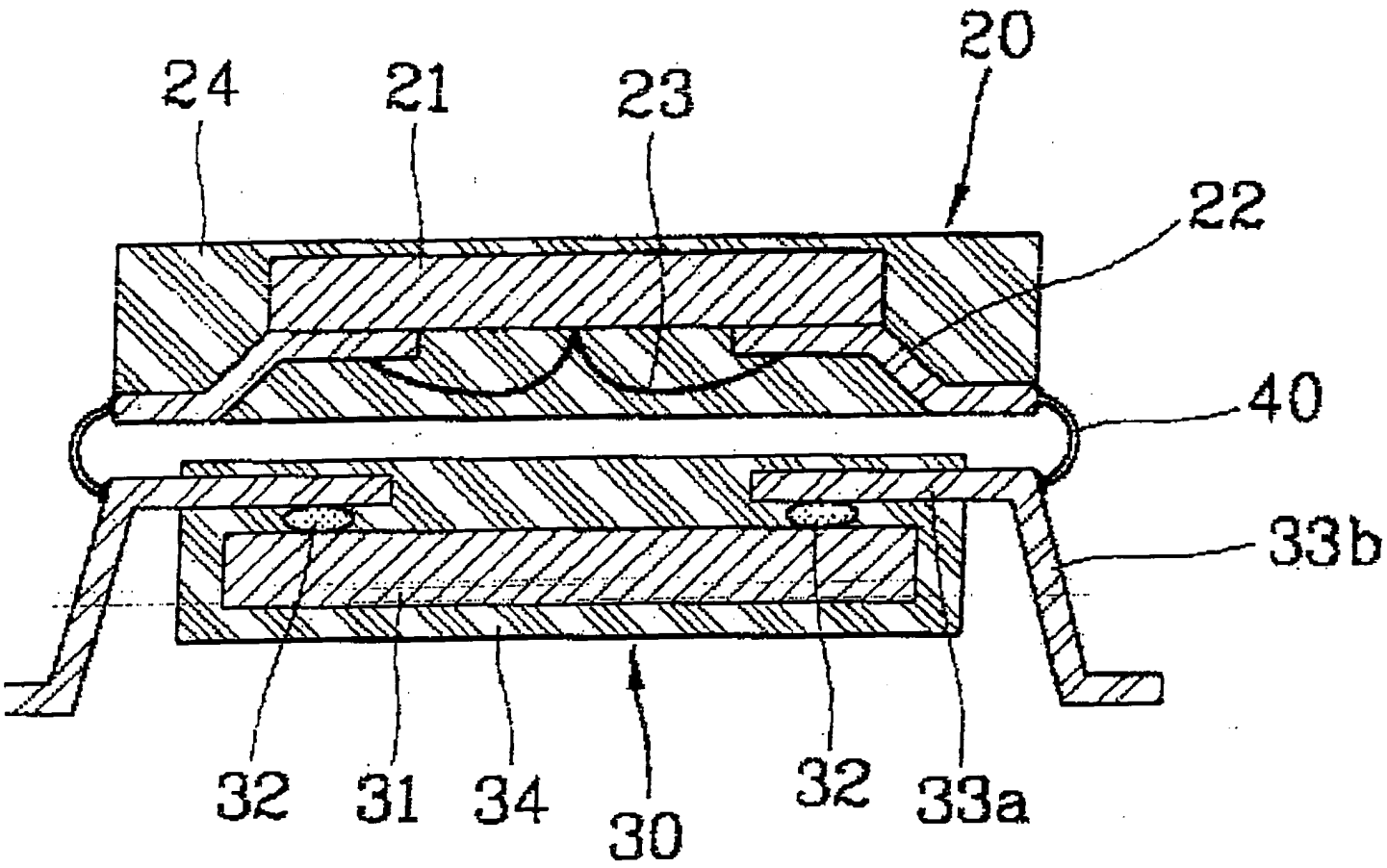
wire(40). In the upper single package(20), a plurality of leads(22) are attached to bottom both sides of a semiconductor chip(21), the leads(22) are respectively wired by metal wires(23). The chip(21), metal wires(23) and leads(22) are molded by encapsulant(24). In the ower single package(30), inner leads(33a) are attached to top both sides of a chip(31) through bumps(32). The inner leads(33a), the chip(31) and bumps are molded by encapsulant(34).

CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS: STACK TYPE PACKAGE

DERWENT-CLASS: U11

EPI-CODES: U11-C;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